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(54) **RESIN SEALING METHOD OF SEMICONDUCTOR CHIP**

(57)Abstract:

PURPOSE: To improve moisture resisting reliability, by pretreating a semiconductor chip with chloroalkylsilane expressed by R_2SiCl_2 or/and $RSiCl_3$, and thereafter performing resin sealing.

CONSTITUTION: Chloroalkylsilane expressed by R_2SiCl_2 or/and $RSiCl_3$ including an alkyl group of C_3WC_{20} or a phenyl group R is dissolved in toluene or the like and applied on the surface of a chip. After drying, the surface is washed with toluene or the like, and the excessive silane treating agent is washed away. After drying, epoxy resin sealing is performed. In this constitution, adhesion between the chip and the resin is improved, and the moisture resisting reliability is improved.

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